


EP-TeQ is proud to announce that we are present at  **electronica**
inside tomorrow

8-11 November, 9:00 - 17:00, Messe München

Please mark your calendar and give us a call or an email with your interest and planned attendance, in order for us to book time slots for demos/meetings at the specific suppliers' booths.

Lars Kongsted-Jensen	+45 20 98 37 30	Director
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Please see NEWS & HIGHLIGHTS of our machines and tools presented at the exhibition, including supplier booth numbers.

Click on the product headlines for more information.

News & Highlights at electronica 2016



PCB Design Tool Suite from Altium (Michael/Petri)

A1.572

- ✓ NEW PCB design technology in Altium Designer 17, featuring:
 - ActiveRoute™
 - Dynamic Copper
 - Backdrilling
 - Auto Cross-Probing
 - Track Glossing



DfT & Coverage Analysis from Aster Technologies (Lars/Petri)

A1.352

- ✓ DPMO reduction
A calculation of volume of defects that will not occur due to solder paste inspection.
- ✓ Optimized test programs
By using test balancing (test distribution) over the manufacturing line - reduced test program (easier debug, faster to execute) and higher throughput (increased revenues).
- ✓ Updated Takaya exporter
Optimise IC is analysing Open-Checker and Diode test coverage, to keep the best test only. Significant test time reduction.
- ✓ New scripts developed
To report test coverage in more readable format (PCOLA_report.scr; PPVS_report.scr)
- ✓ Reworked cost modelling: ICT_cost_model.scr + FPT_cost_model.scr



JTAG/Boundary Scan test/ESA from Göpel electronic (Lars/Petri)

A1.351

- ✓ NEW product, Gcat (Gigabit Cable Tester)
For validation and low volume test of high speed interconnect cables
- ✓ SCANFLEX II Cube: Next generation ESA Desktop system
- ✓ Embedded fixture solution for BER test of USB3.0 high speed interfaces
- ✓ JEDOS (embedded diagnostic operating system) for ZYNQ and iMX6



SPI from Göpel electronic (Knud/Michael/Petri)

A1.351

- ✓ NEW software for even higher user friendliness and faster test program generation.



AOI from Göpel electronic (Knud/Michael/Petri)

A1.351

- ✓ NEW - Fastest 3D AOI all-rounder, VarioLine, thanks to 3D, five-angled camera module
- ✓ THT-Line: AOI system for parallel THT component & solder joint inspection
- ✓ BasicLine 3D: Powerful stand-alone AOI - 3D technology also for manufacturers of smaller batches



In-Line AXI from Göpel electronic (Knud/Michael/Petri)

A1.351

- ✓ X-Line 3D: Inline X-ray system for comprehensive inspection of complex assemblies.
- ✓ PILOT Connect: Import of different inspection data, even from external systems, for central data management.



Fixtureless In-Circuit Test (ICT) Flying Probe test from Takaya

A1.243

- ✓ NEW - Integration of BScan into the TAKAYA APT1400 – Live demo! (Lars/Petri)



Probes from Everett Charles Technologies (ECT) (Knud/Michael/Petri)

A1.268

- ✓ High Current Spring Probes
 - 8 different high current rating from 10 Amps up to 150 Amps DC
 - advanced architecture to reduce arcing, increase contact points and lower resistance
 - designed for most challenging industrial test applications (automotive, military, ect.)
- ✓ LFRE ICT/FCT Spring Probes
 - significantly harder plating than the industry standard
 - breaks through oxides and debris for reliable electrical contact
- ✓ EDGE™ Spring Probes for challenging ICT/FT test
 - significantly harder plating than the industry standard
 - breaks through oxides and debris for reliable electrical contact
- ✓ RF Coaxial Probes
 - instrumentation-quality 50 Ohm impedance
 - RF measurement up to 20 GHz





Fixtures from Everett Charles Technologies (ECT) (Knud/Michael/Petri)

A1.268

- ✓ *NEW - Fixture Press Adapter (Cassette/Receiver) – Live demo!*
 - low cost fixturing cassettes - low weight fixturing cassettes
 - medium - high node count (3000 probes)
- ✓ *NEW - Mechanical Benchtop Cassette/Receiver System – Live demo!*
 - low cost - low weight - small footprint - desktop solution
 - ideal for lower volume and/or development testing of PCBAs
- ✓ *VG Series Mass Interconnect Solutions*
 - lowest cost of ownership
 - single interface item to fully customized solutions
- ✓ *Zoom Fixturing*
 - 0.38mm test range target on 0.6mm pitch - reliable wire-warp assembly
 - typically 170g (60oz) probe force - available on all ICT test platforms

We are looking forward to seeing you in Munich - hopefully also at our Nordic/Baltic networking dinner Wednesday evening!

Best regards,

Knud Vester

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